

### **Abstract**

A product and process for bonding porous materials, such as piezoelectric materials, to substantially non-porous substrates is described. The non-porous substrate contains a plurality of apertures extending through the bonding surface. Adhesive is dispensed on the bonding substrate to at least partially fill the apertures. The porous material is then pressed against the bonding surface and the combination is cured. During curing, a portion of the adhesive is absorbed into the porous material from the apertures, however, sufficient adhesive remains in the apertures to bond the porous material to the substantially non-porous substrate.